

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in this application:

LISTING OF CLAIMS:

1. (Original) An inductive sensor, comprising:
at least two circuit boards;
receiver circuit traces arranged on a first one of the circuit boards; and
components of an evaluation electronic arrangement configured to evaluate signals that originate from the receiver circuit traces arranged on a second one of the circuit boards;
wherein the circuit boards are joined in a sandwich manner, at least one component of the evaluation electronic arrangement arranged between the circuit boards.
2. (Original) The inductive sensor according to claim 1, wherein the components of the evaluation electronic arranged are arranged on both sides of the second one of the circuit boards.
3. (Original) The inductive sensor according to claim 1, wherein the first one of the circuit boards includes a recess configured to accommodate at least one of the components of the evaluation electronic arrangement.
4. (Original) The inductive sensor according to claim 1, wherein at least one of the circuit boards includes an at least partially circumferential ridge arranged to at least partially cover a gap between the circuit boards joined in the sandwich manner.
5. (Original) The inductive sensor according to claim 4, wherein the ridge is arranged on a cylindrical shell side of the at least one of the circuit boards.
6. (Original) The inductive sensor according to claim 1, wherein the first one of the circuit boards and the second one of the circuit boards are joined to each other at least one of mechanically and electrically by a soldered connection.

7. (Original) The inductive sensor according to claim 1, wherein the first one of the circuit boards and the second one of the circuit boards are joined to each other by a bonded connection.

8. (Original) The inductive sensor according to claim 1, wherein the first one of the circuit boards and the second one of the circuit boards are joined to each other by a welded connection.

9. (Original) The inductive sensor according to claim 1, further comprising a filler material arranged to fill a volume between the circuit boards.

10. (Original) An inductive sensor, comprising:
at least two circuit boards, a first one of the circuit boards including a recess;
receiver traces arranged on the first one of the circuit boards; and
components of an evaluation electronic arrangement configured to evaluate signals that originate from the receiver circuit traces arranged on a second one of the circuit boards;

wherein the circuit boards are joined in a sandwich manner, at least one component of the evaluation electronic arrangement arranged in the recess of the first one of the circuit boards and between the first one of the circuit boards and the second one of the circuit boards, the circuit boards connected to each other at least one of electrically and mechanically by a solder connection.

11. (Original) A rotary encoder, comprising:
an inductive sensor, including:

at least two circuit boards;
receiver circuit traces arranged on a first one of the circuit boards; and
components of an evaluation electronic arrangement configured to evaluate signals that originate from the receiver circuit traces arranged on a second one of the circuit boards;

wherein the circuit boards are joined in a sandwich manner, at least one component of the evaluation electronic arrangement arranged between the circuit boards.

12. (New) The inductive sensor according to claim 1, further comprising at least one excitation coil arranged on the first circuit board.

13. (New) The inductive sensor according to claim 10, further comprising at least one excitation coil arranged on the first circuit board.

14. (New) The rotary encoder according to claim 11, wherein the inductive sensor includes at least one excitation coil arranged on the first circuit board.